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Influence of nitrogen content on Ni_xN thin films deposited by reactive magnetron sputtering.

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The Ni-N system can be crystallized in many phases. Two Ni_xN_y phases are stable, Ni₄N which crystallizes in cubic phase and Ni₃N which crystallizes hexagonal phase. Some recent study highlighted a third structure corresponding to Ni₂N. Other phases such as Ni₃N₂ et Ni₆ have been synthesized by chemical processes but never by reactive magnetron sputtering. Most studies, related to NiN by reactive sputtering, report a mixture of nitrided phases. Ni₄N reveals ferromagnetic behavior while Ni₃N and Ni₂N are paramagnetic. This material can also be used as negative electrode for Li battery and solar cells. Furthermore, Ni_xN can also be used as resistive switch.

This study deals with optimization of DC reactive magnetron deposition process using a pure nickel target (99.995%) in an Ar-N₂ gas mixture with varied nitrogen gas flow and bias voltage (floating or -100V).

The characterization of the NiN films has been carried out by X-ray diffraction (XRD), X-ray photoelectrons spectroscopy (XPS), Energy dispersive X-ray Spectroscopy (EDXS), SEM and AFM.

XRD measurements have highlighted the deformation of the Ni cubic cell as a function of nitrogen content and a mixture of nitrided phases (Ni₄N, Ni₃N and Ni₂N) appears for 20% N₂ in the discharge.

XPS and EDX are well correlated. The XPS peaks of N1s situated at 396,2 eV and 397,6 eV are attributed to Ni-N-O and N-Ni bonds and permit us to determine three zones : metallic between 0 and 20% N₂, Ni₄N between 20% and 42% N₂ and finally Ni₃N for higher than 42% N₂. These three zones are in good agreement not only with deposition rate and optical emission spectroscopy measurements but also with roughness, electrical resistivity and hardness.

Keywords

Nickel Nitride

Reactive Sputtering

XPS analysis

XRD